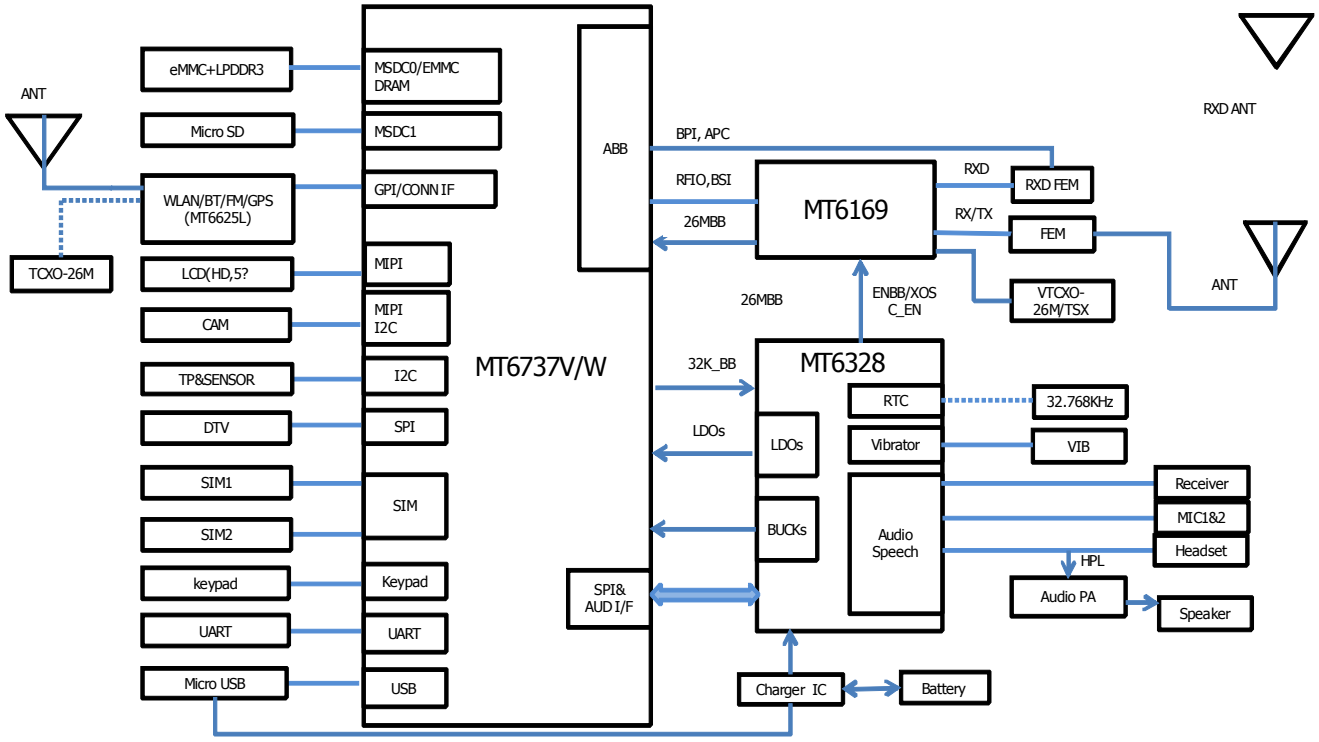
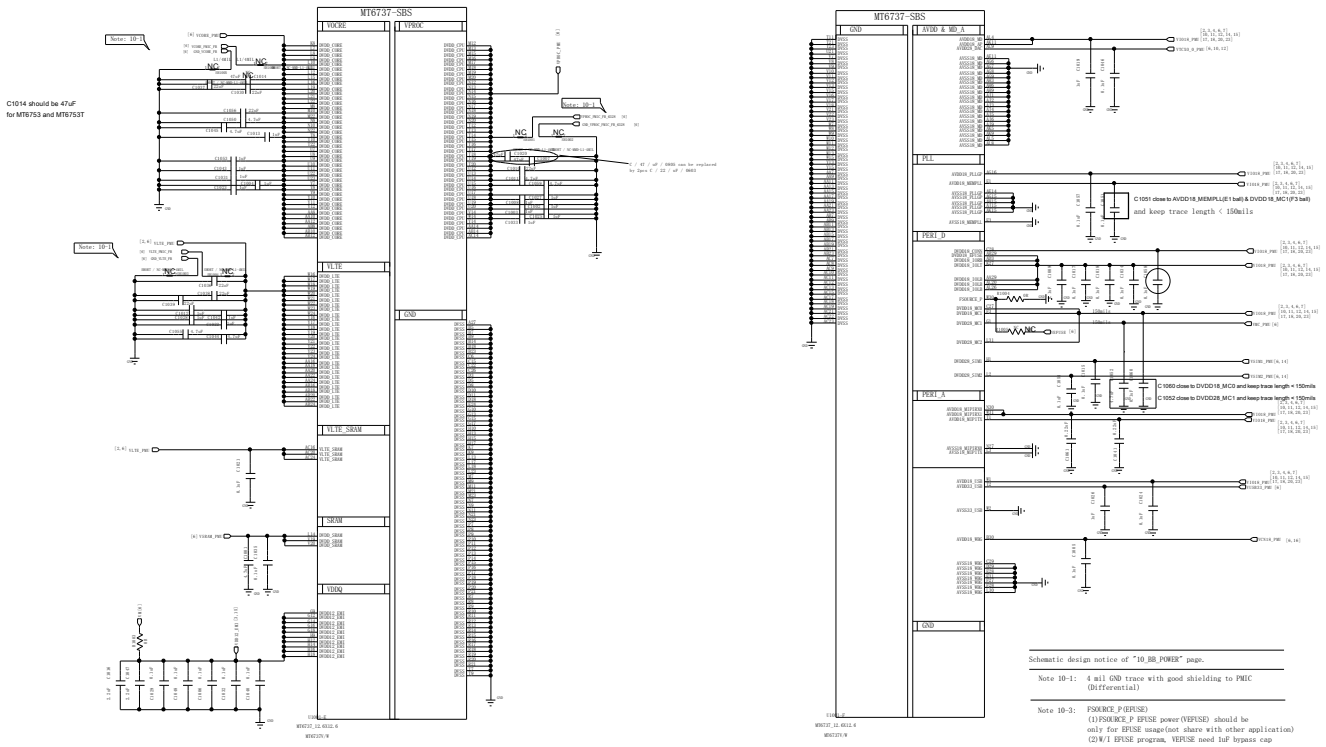
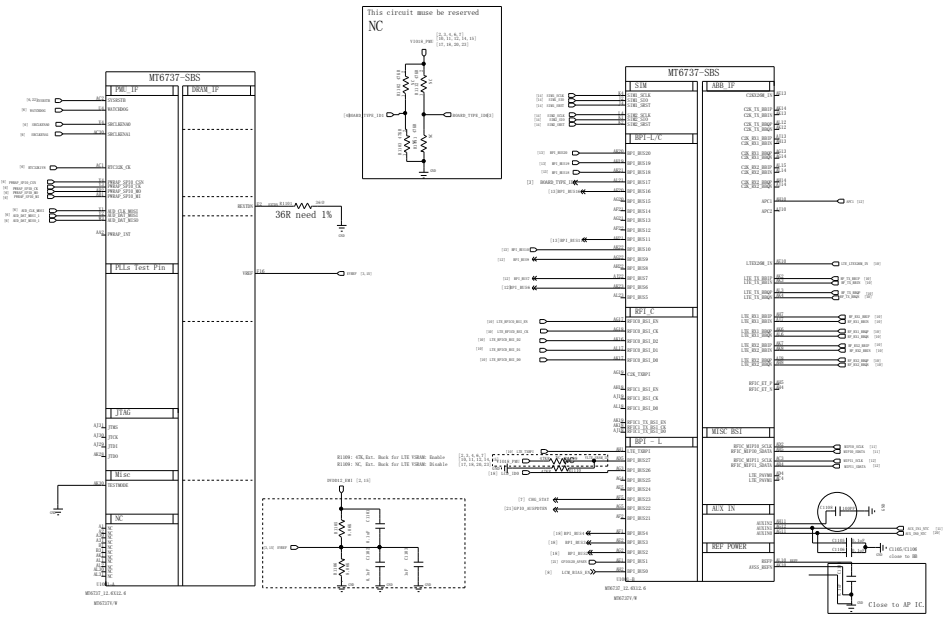

ANT
TCXO-26M
eMMC+LPDDR3
Micro SD
WLAN/BT/FM/GPS
(MT6625L)
LCD(HD,5?
CAM
TP&SENSOR
DTV
SIM1
SIM2
keypad
UART
Micro USB
MSDC0/EMMC
DRAM
MSDC1
GPI/CONN IF
MIPI
MIPI
I2C
I2C
SPI
SIM
Keypad
UART
USB
MT6737V/W
ABB
SPI&
AUD I/F
BPI, APC
RFIO,BSI
26MBB
MT6169
RXD
RX/TX
RXD FEM
FEM
VTCXO-
26M/TSX
RXD ANT
ANT
26MBB
ENBB/XOS
C_EN
32K_BB
LDOs
BUCKs
MT6328
RTC
Vibrator
LDOs
Audio
Speech
32.768KHz
VIB
Receiver
MIC1&2
Headset
HPL
Audio PA
Speaker
Charger IC
Battery

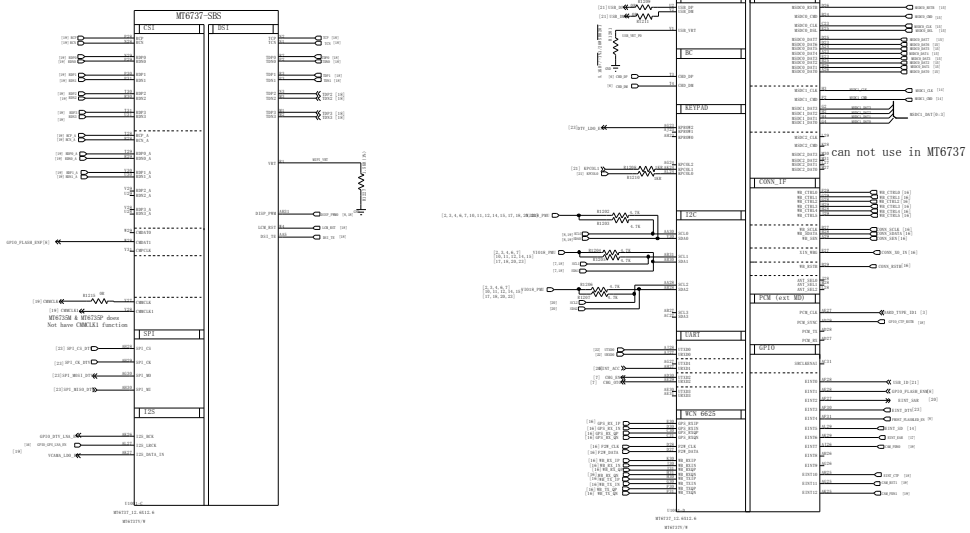


Schematic design notice of "10_BB_POWER" page.

Note 10-1: 4 mil GND trace with good shielding to PMIC (Differential)

Note 10-3: FSOURCE_P(EFUSE)
(1)FSOURCE_P EFUSE power(VEFUSE) should be only for EFUSE usage(not share with other application)
(2)W/I EFUSE program, VEFUSE need 1uF bypass cap (pls refer to "LDO output voltage/current table")
(3)W/O EFUSE program, VEFUSE bypass cap should be NC.


MT6737-SBS
PMU_IF
DRAM_IF
PLLs Test Pin
JTAG
Misc
NC
36R need 1%
This circuit muse be reserved
NC
MT6737-SBS
SIM
AHB_IF
BPI-L/C
BPI_C
BPI - L
MISC BSI
AUX IN
REF POWER
Close to AP IC

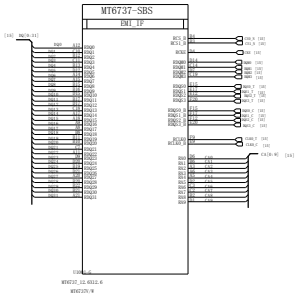


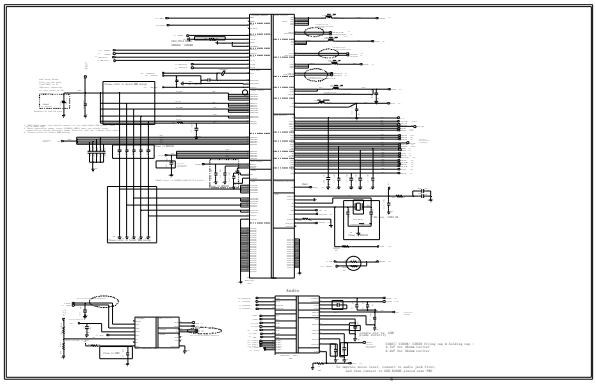
Schematic design notice of "12_BB_2" page.

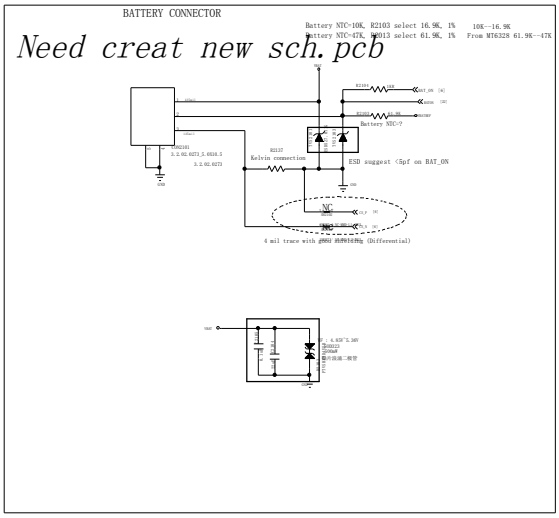
Note 12-1: MSDC2 Pin should be NC (No Connection) for MT6735M

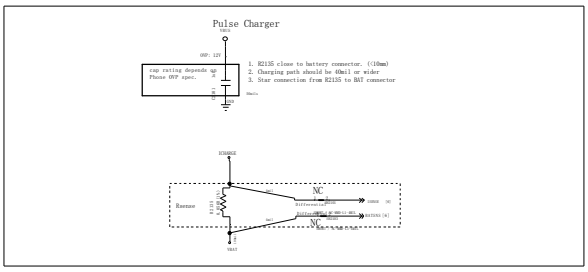
Note 12-2: MT6735M does Not have CMMCLK1 function

Please refer to MT6735M Design Notice for details

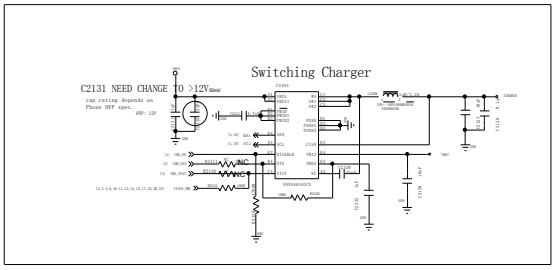

MT6737-SBS
EMI_IF
MT6737_LQ_6531L-6
MT6737SV/W


Audio
Audio
Audio



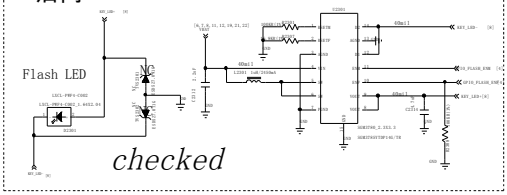


漏电保护删除注意VBAT网络

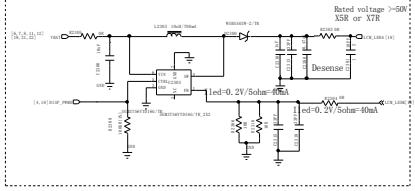


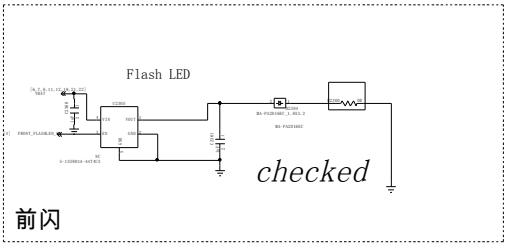
Flash LED

后闪



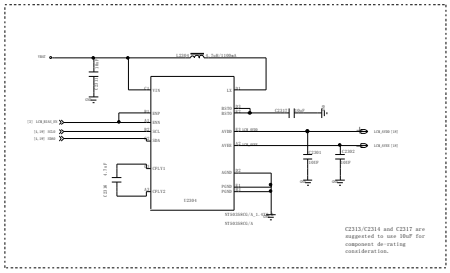
LCM Backlight LED Driver





LCM Gate Drive

LCM Gate Driver I2C address: 0X3E (Write:0x7C, Read:0x7D)

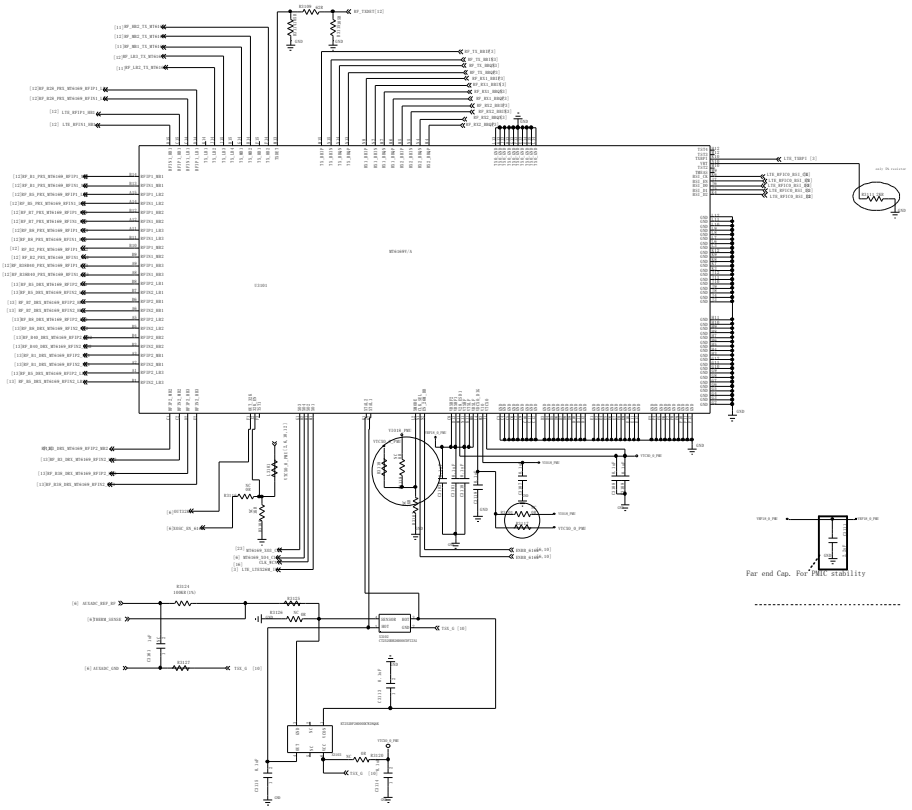


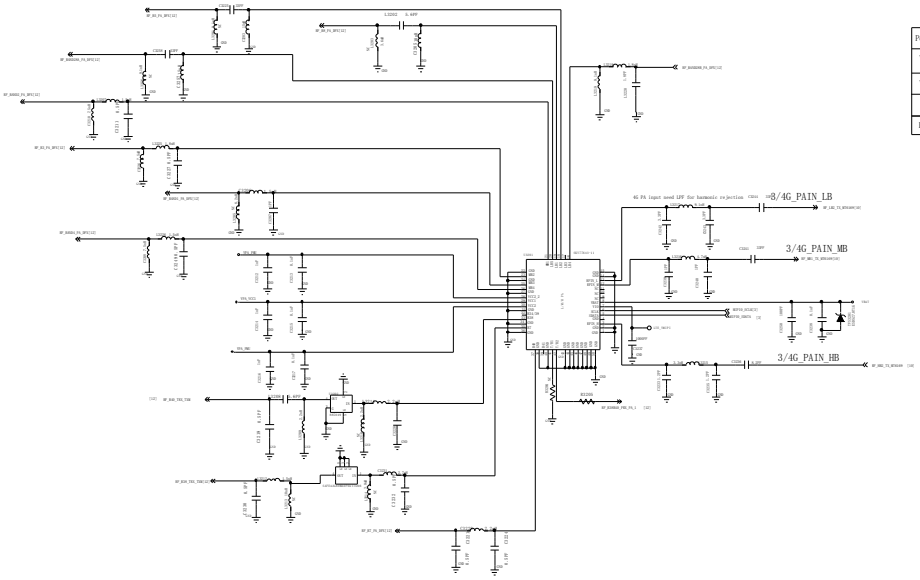
have checked

External Buck for DRAM

If using external buck for DRAM application, please refer to "MT6735_53 DRAM External Buck Design Notice":
1. Please add one more 1uF capacitor on PMIC VM output side (Must)
2. Please turn off Fast Transient Function of PMIC VM LDO (Must)

Power trace	PCB line width	MAX current
VRF18_0_PMU	0.4mm	
VIO18_PMU	0.35mm	
VTCXO_0_PMU	0.2mm	

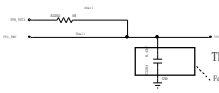




Power trace	PCB line width	MAX current
VPA_PMU	1.1mm	
VPA_VCC1	0.5mm	
VBAT	0.15mm	
LTE_VMIPI	0.15mm	

Thermistor / To sense board level temperature

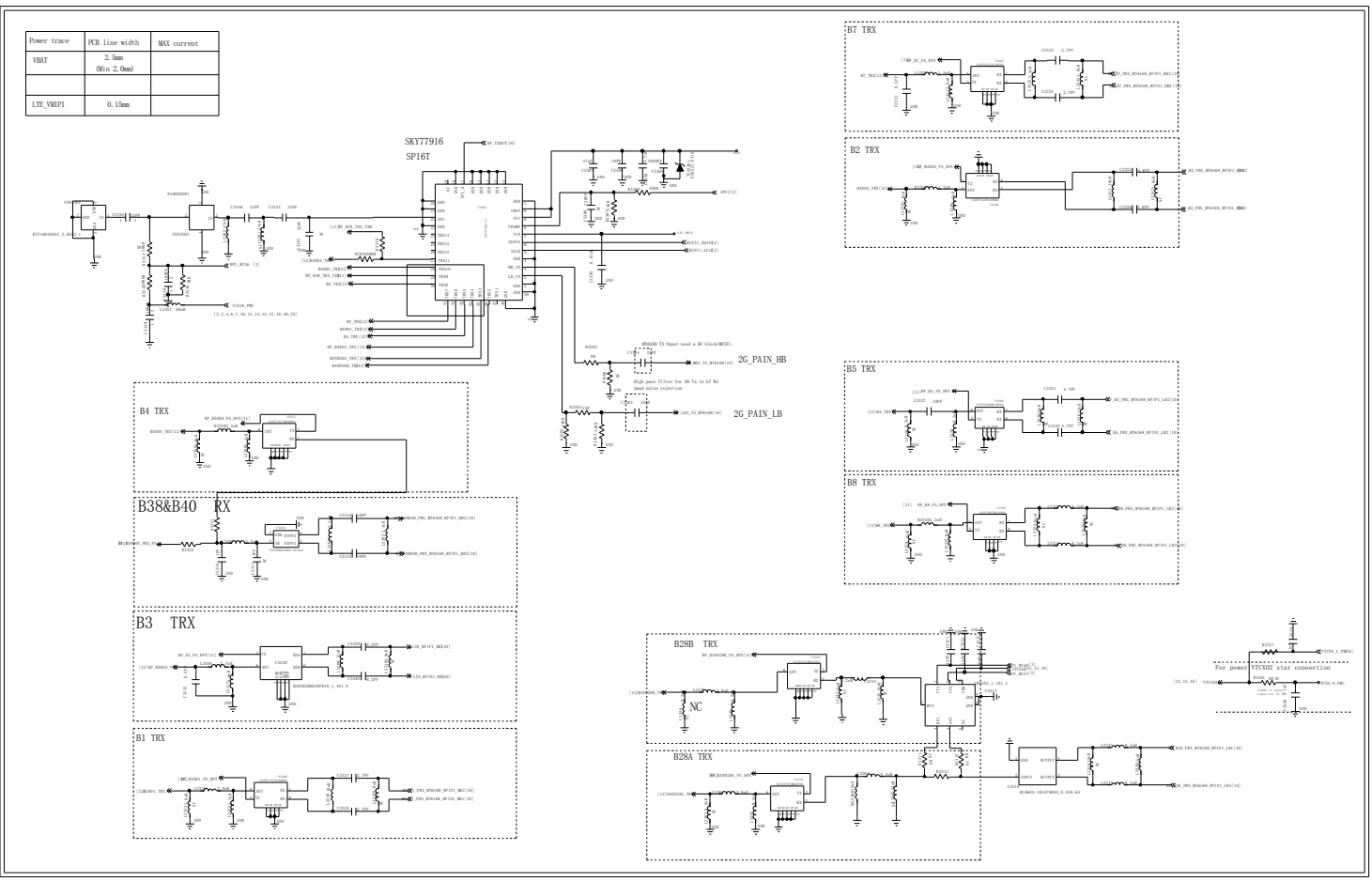
VPA_VCC1 and VPA PMU need to be connected after Cap



Thermistor / To sense board level temperature

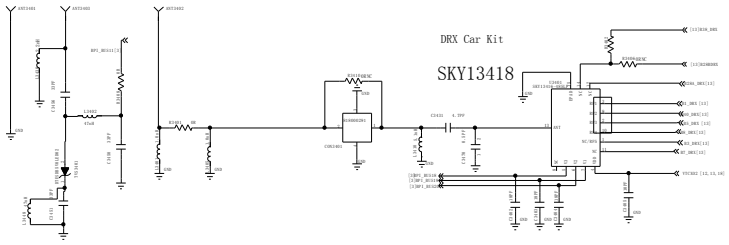
Far end Cap. For PMIC stability

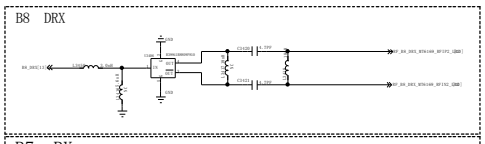
Power trace	PCB line width	MAX current
VBAT	2.5mm (Min 2.0mm)	
LTE_VMIPI	0.15mm	

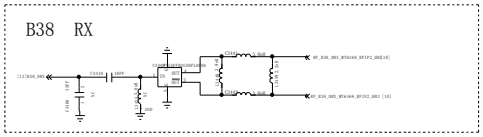


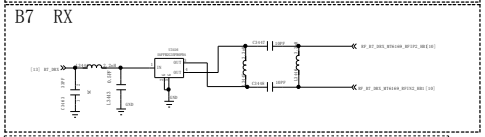
101-23=78

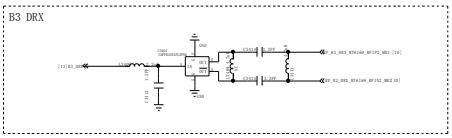
Power trace	PCB line width	MAX current
VTCXO2	0.15mm	50uA

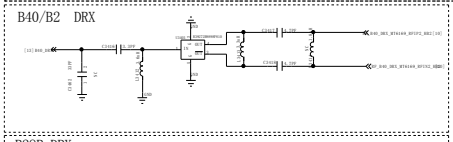


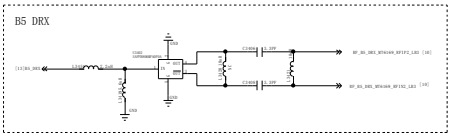


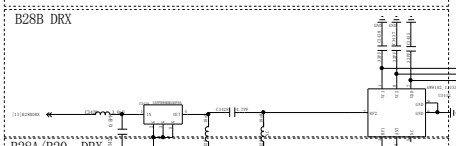


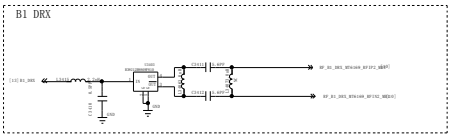


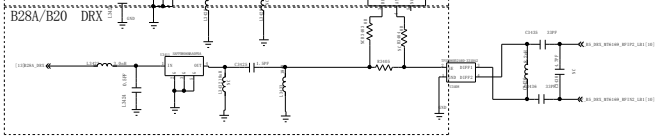






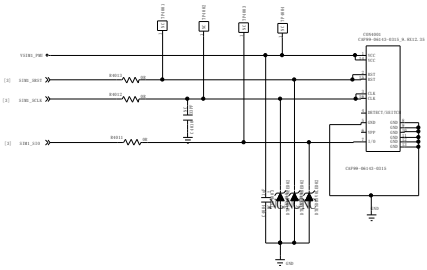






SIM1_sclk & SIM2_sclk sheilding by GND

SIM1



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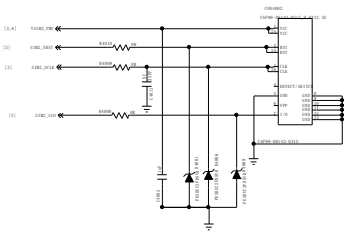
SIM2



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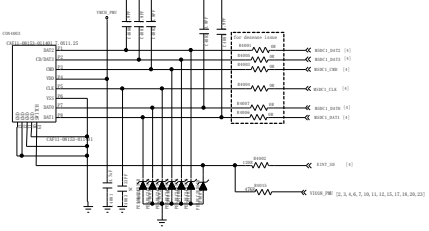
TF card



checked

Connect to AP

DQ[0..31]	DQ[0..31]
CA[0..9]	CA[0..9]
CS0_N	CS0_N
CS1_N	CS1_N
CKE	CKE
DQM0	DQM0
DQM1	DQM1
DQM2	DQM2
DQM3	DQM3
DQS0_C	DQS0_C
DQS1_C	DQS1_C
DQS2_C	DQS2_C
DQS3_C	DQS3_C
DQS0_T	DQS0_T
DQS1_T	DQS1_T
DQS2_T	DQS2_T
DQS3_T	DQS3_T
CLK0_T	CLK0_T
CLK0_C	CLK0_C
VREF_CA	VREF_CA
VREF_DQ	VREF_DQ
MSDC0_RSTB	MSDC0_RSTB
MSDC0_CMD	MSDC0_CMD
MSDC0_CLK	MSDC0_CLK
MSDC0_DSL	MSDC0_DSL
MSDC0_DAT0	MSDC0_DAT0
MSDC0_DAT1	MSDC0_DAT1
MSDC0_DAT2	MSDC0_DAT2
MSDC0_DAT3	MSDC0_DAT3
MSDC0_DAT4	MSDC0_DAT4
MSDC0_DAT5	MSDC0_DAT5
MSDC0_DAT6	MSDC0_DAT6
MSDC0_DAT7	MSDC0_DAT7

Power I/F

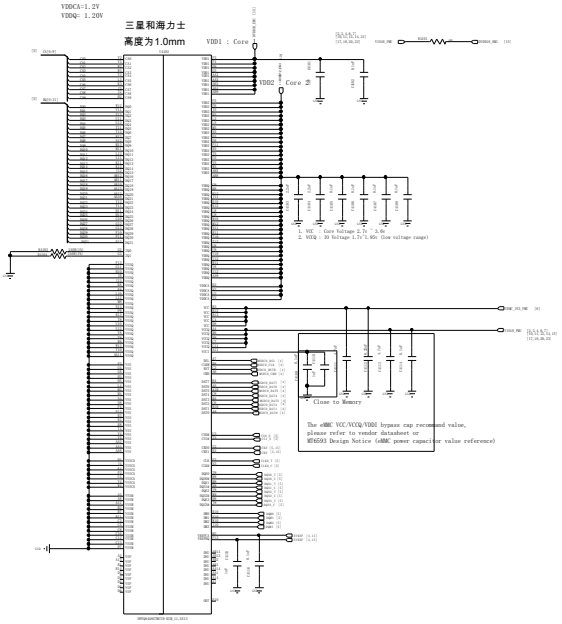
VIO18_PMU	VIO18_PMU
VEMC_3V3_PMU	VEMC_3V3_PMU
DVDD12_EMI	DVDD12_EMI

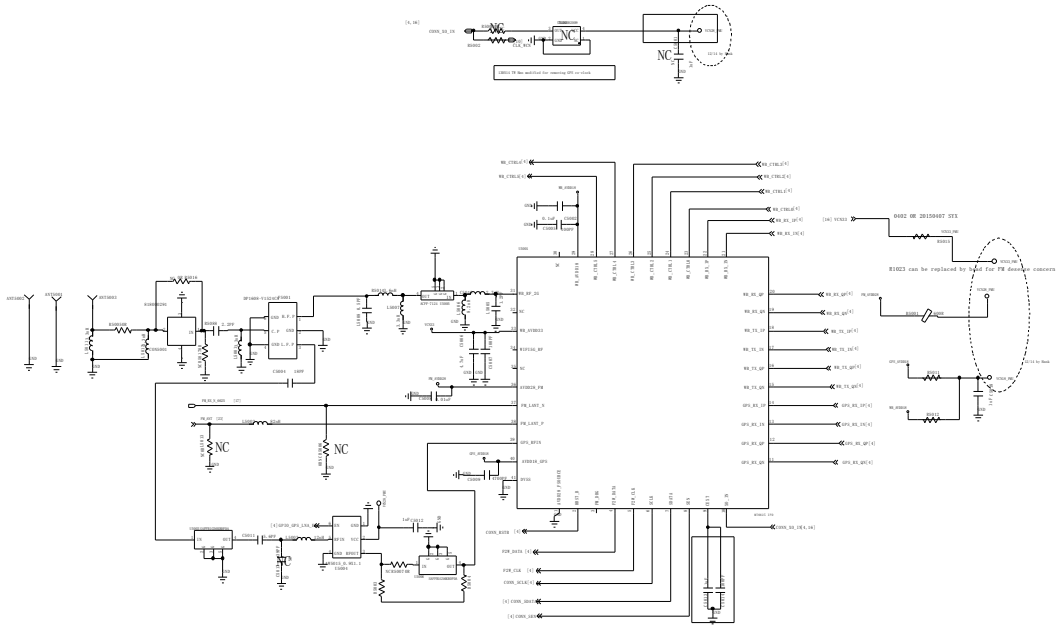
eMMC+LPDDR3 16GB eMMC + 8Gb LPDDR3

221 Ball, 0.5mm pitch

VDD1=1.8V
VDD2=1.20V
VDDCA=1.2V
VDDQ= 1.2V

三星和海力士
高度为1.0mm



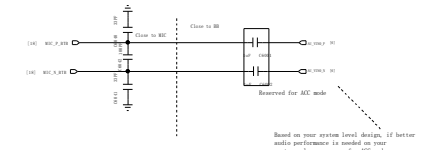

NC
NC
NC
NC
NC
0402 OR 20150407 STX
R10C3 can be replaced by bead for PB desense concern

Speaker NC

Based on your system level design , if better dessense performance is needed on your system.

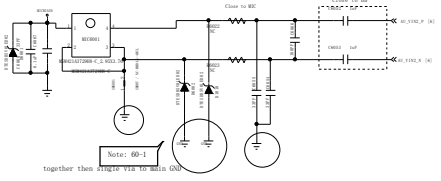
Based on your system level design , if better ESD performance is needed on your system.

Handset Microphone 1



Based on your system level design, if better audio performance is needed on your system, please reserve for ACC mode

Second MIC NC



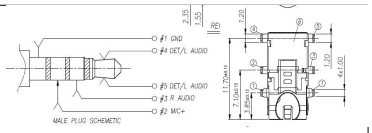
checked

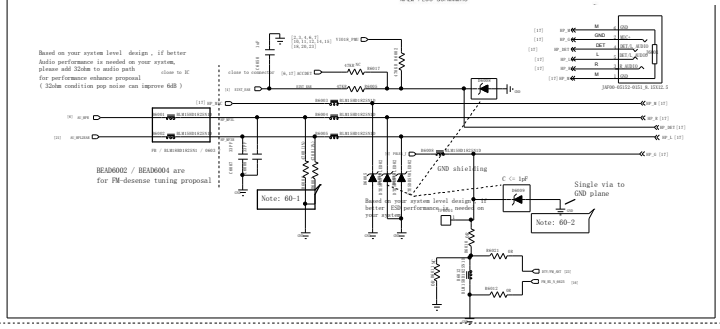
Earphone Audio 美标

DIMENSION IN mm	Shenzhen Linkconn Electronics Co.,Ltd.
TOLERANCE UNLESS OTHERWISE SPECIFIED	
.XX±0.05	APR. 2
.XXX±0.25	CHK. JC
.XXXX±0.15	DRA. 2010/05/27

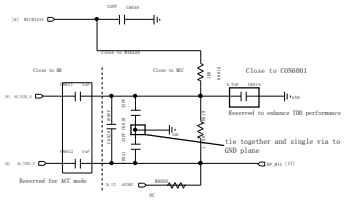
MOD: Ø3.5 AUDIO JACK (DIP) INSERT TYPE
DWG NO. JAF00-0515Z-0151
CUSTOMER DRAWING
SHT 1/4 SCALE 3:1 SHEET 2 REV A

(1) iPhone : L-R-G-M

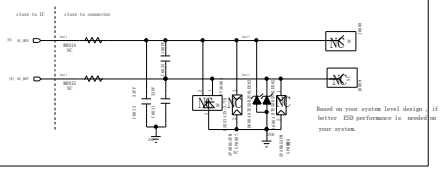


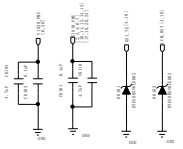


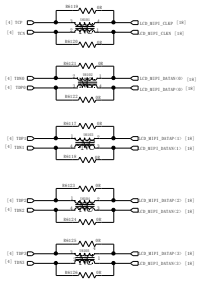
Earphone MICPHONE



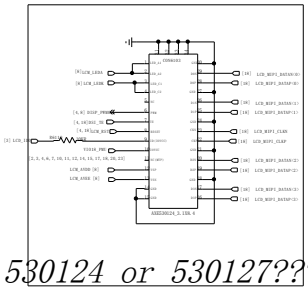
Receiver





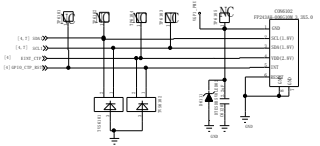


屏连接器

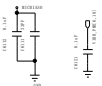


530124 or 530127???

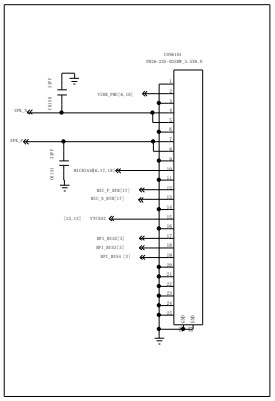
define pin accord customer CTP



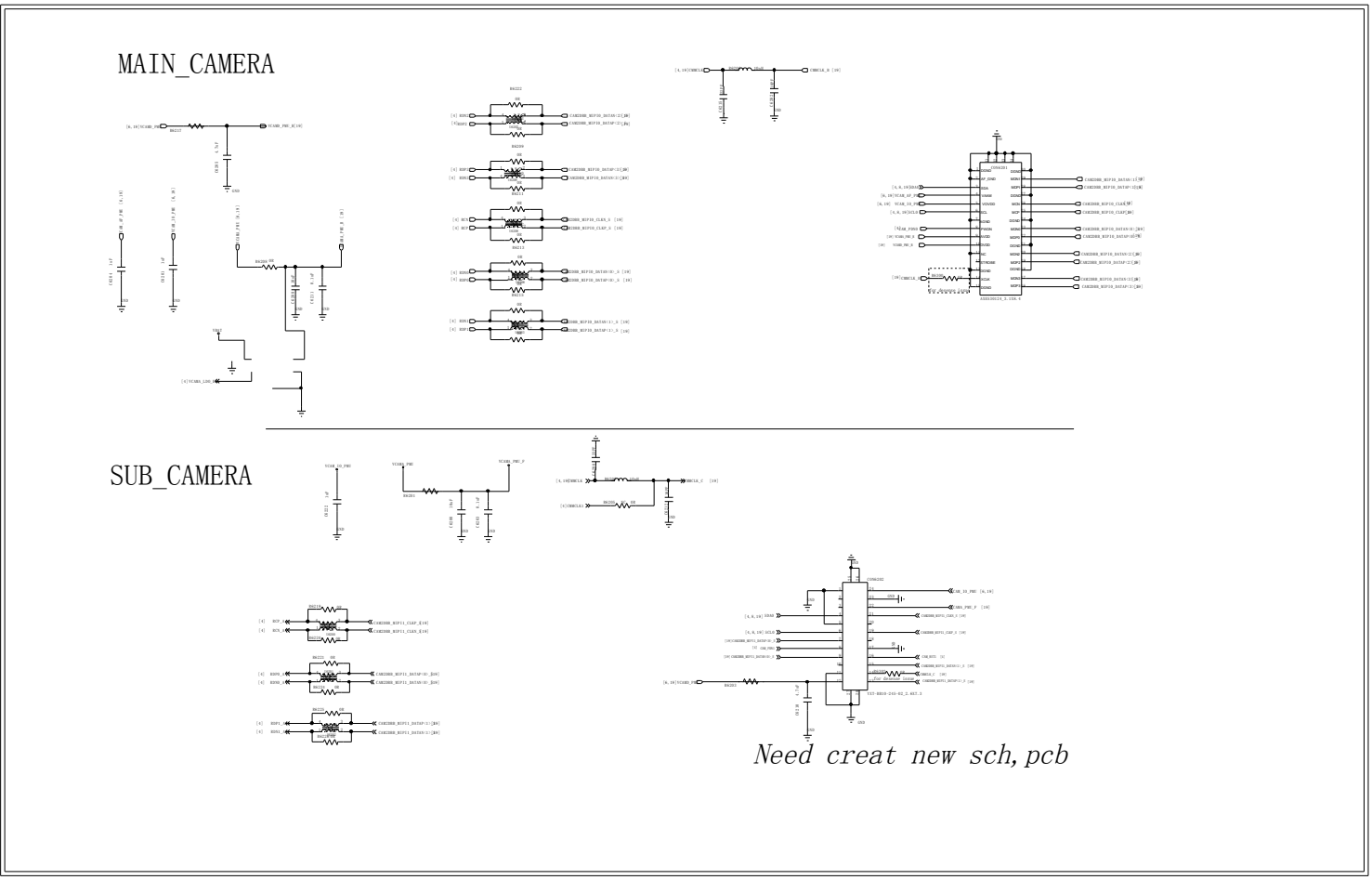
checked



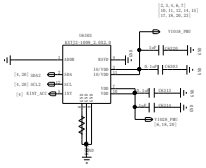
25PIN大小板连接器ZIF



camera需要参考最新的部件



G Sensor-3X



CS=1: I1C

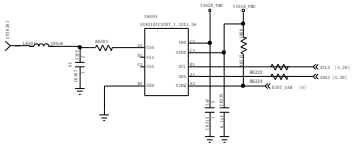
LIS3DHTR : SA0=0: I1C ADDRRSS is 0x18H
KXCJK-1113 : SA0=0: I1C ADDRRSS is 0x1DH
power down(communicating), I = 0.5uA

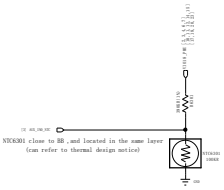
Configuration VS Chip

Fuction	U3001	C3004	C3005	C3006	R3003
G-Sensor	LIS3DHTR	NC	NC	NC	0
G-Sensor	KXCJK-1113	NC	NC	NC	0

Default LIS3DHTR

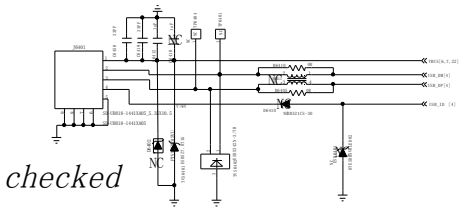
SAR Sensor

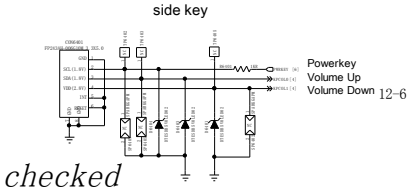


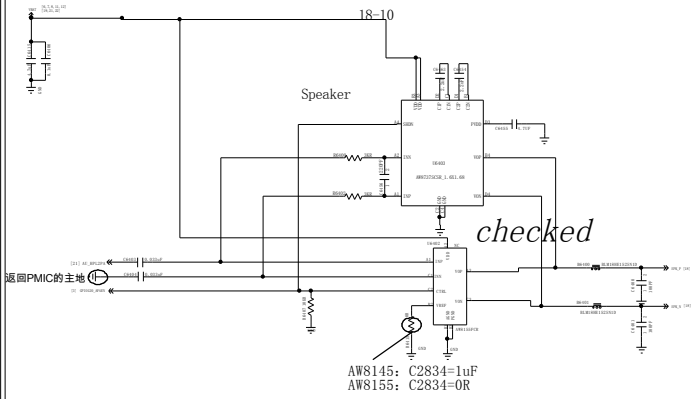


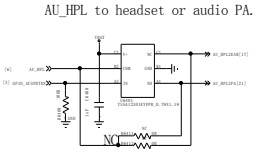
Thermistor / To sense board level temperature

have checked


NC
NC
NC
NC
checked


side key
Powerkey
Volume Up
Volume Down
12-6
checked

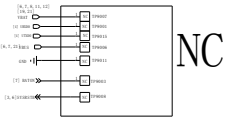

18-10
Speaker
checked
返回PMIC的主地
AW8145: C2834=1uF
AW8155: C2834=0R


AU_HPL to headset or audio PA.
NC

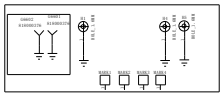
UART只是测试不按照生产要求

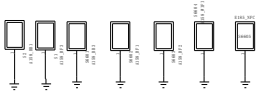
开关机键电源键，USB按照生产要求摆放2.5mm

TEST POINTS

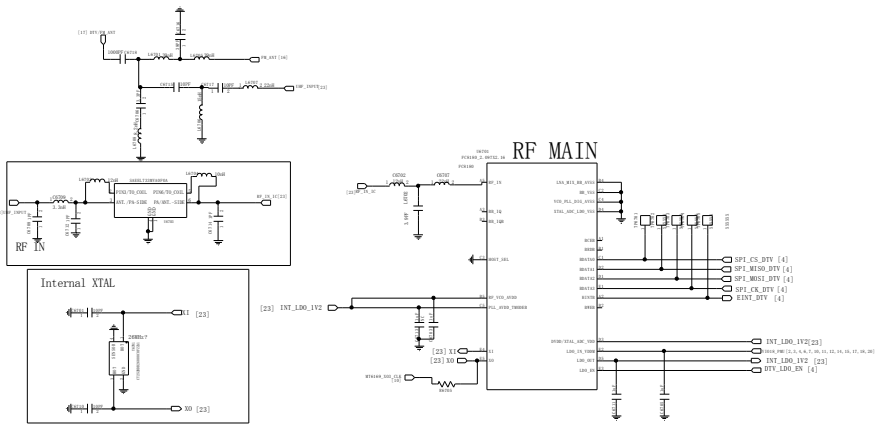


接地弹片改818000376





have checked


RF MAIN
RF IN
Internal XTAL
[23] INT_LDO_1V2
[23] X1
[23] X0
SPI_CS_DTV [4]
SPI_MISO_DTV [4]
SPI_MOSI_DTV [4]
SPI_CK_DTV [4]
EINT_DTV [4]
INT_LDO_1V2 [23]
INT_LDO_1V2 [23]
DTV_LDO_EN [4]